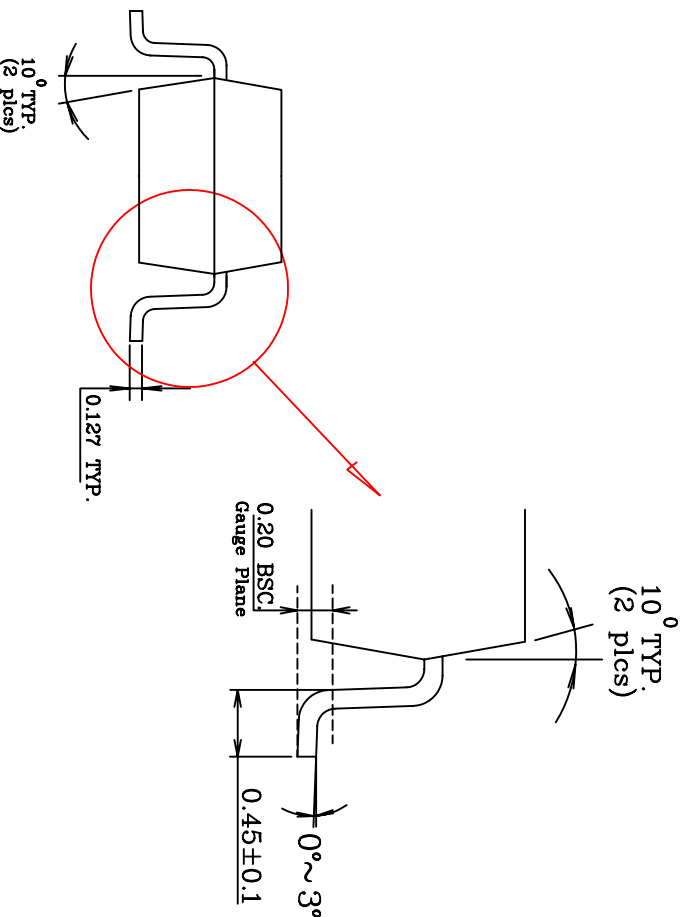


- NOTE:
1. Dimensions and tolerances are as per ANSI Y14.5M, 1982.
 2. Package surface to be mirror finish.
 3. Die is facing up for mold. Die is facing down for trim/form, ie. reverse trim/form.
 4. The footlength measuring is based on the gauge plane method.
- △ Dimensions are exclusive of mold flash and gate burr.



COPPER FRAME

F	NOTE: METAL BURR REVISE TO GATE BURR AS PER JEDEC SPEC. LEAD WIDTH CHANGE TO 0.35-0.50 (WAS 0.36-0.52) AS PER JEDEC SPEC.	18/01/02	ANDREW	PT
E	ADD NOTE NO.5.	15/01/01	ANDREW	PT
Δ	CHANGED LEAD WIDTH TO 0.36(MIN)&0.520(MAX) - (WAS 0.4)	03/06/99	ANDREW	PT
C	CHANGED L/F MATERIAL TO C7025 (1/2H) 5 MILS (WAS A42, 4 MILS).	30/08/97	CH TAN	CH TAN
B	CHANGED SPEC. TO MEET JEDEC.	11/01/96	CH TAN	CH TAN
A	ORIGINAL DESIGN.	08/12/94	CH TAN	CH TAN

REV.	DESCRIPTION	DATE	BY	APPD

TOLERANCES REFER TO THE SPECIFICATION ABOVE.

UNIT:	MM
SCALE:	NTS
SYMBOL	

DWN:	ANDREW	DATE:	18/01/02
APPD:	CH TAN	DATE:	
APPD:	CK TANG	DATE:	
APPD:	CW CHAI	DATE:	
APPD:	SRI	DATE:	
DWG. NO.:	SOT-P-C05	REV.:	F

Reference to Jeduc Spec # : M0178 Issue A.

SOT-23 (5 LDS)
PACKAGE CASE OUTLINE